

Atty. Docket No. CPAC.1001-1
Appl. No. 09/802,443



PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra D. PENDSE, *et al.*

Application No.: 09/802,443

Filed: March 9, 2001

Title: Flip chip-in-leadframe package and
process

Examiner: Victor V. Yevsikov

Group Art Unit: 2825

Date: February 13, 2004

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on February 13, 2004.

Signed

Paula Faulk Hurley
Paula Faulk Hurley

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

Responsive to the Office action mailed August 13, 2003, kindly amend the application as follows:

Amendments to the claims are reflected in the Listing of Claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.

OK TO ENTER V.G.